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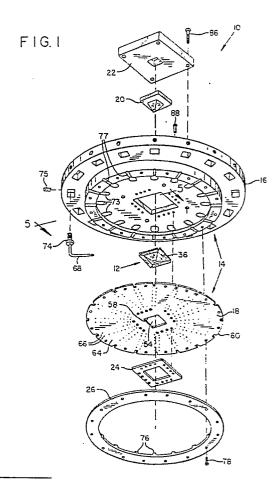
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- 54 Semiconductor wafer probe.
- (57) A flexible thin film probe head extends below a probe frame and supports a plurality of wafer contact bumps in planar array. An elastic member is positioned between a rigid plate and the surface of the thin film opposite the contact bumps so as to provide a controlled pressure interconnect between the I/O pads on the wafer and the contact bumps. Interface between the contact bumps and external test equipment is made through constant impedance transmission lines on the probe head and on an adjoining substrate. The two sets of transmission lines are coupled together by mechanical pressure contacts so as to facilitate the substitution of other probe heads having different wafer I/O pad configumrations. Interface between the transmission lines on the printed circuit board and a set of semirigid coaxial cables is made by a second pressure interface so as to simplify assembly of the unit.



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EUROPEAN SEARCH REPORT

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